SIDE- LOOK PACKAGE PIN PHOTO DIODE

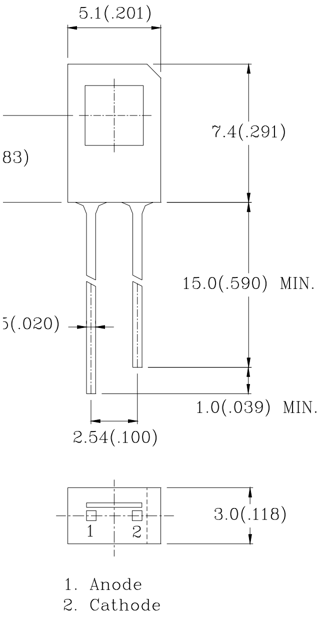
● Features

1. Wide receiving angle
2. Linear response vs. irradiance
3. Fast switching time
4. Side-looking Package ideal for space Limited applications
5. Lens Appearance: Water Clear

● Description

The BPD-RQ03DV-1 device consists of a PIN silicon photodiode molded in a clear epoxy package which allows spectral response from visible to infrared light wavelengths. The wide receiving angle provides relatively even reception over a large area. The side-looking package is designed for easy PC board mounting. This photodiode is mechanically and spectrally matched to BRIGHT's GaAs and GaAlAs series of infrared emitting diodes.

●Package Dimensions:



NOTES:
1.All dimensions are in millimeters (inches).
2.Tolerance is ±0.25mm (0.01”) unless otherwise specified.
3.Lead spacing is measured where the leads emerge from the package
4. Specifications are subject to change without notice

● Absolute Maximum Ratings(Ta=25℃)

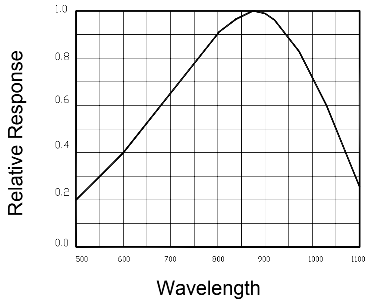
Parameter	Maximum Rating	Unit
Power Dissipation	100	mW
Reverse Breakdown Voltage	60V	
Operating Temperature	-45℃~+85℃	
Storage Temperature Range	-45℃~+100℃	
Lead Soldering Temperature	260℃ for 5 seconds	

● Electrical Characteristics (TA=25℃ unless otherwise noted)

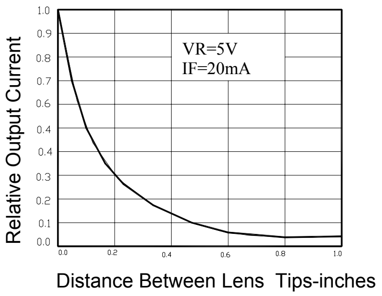
PARAMETER	SYM BOL	MIN	TYP	MAX	UNITS	TEST CONDITIONS
Reverse Light Current	I_L	-	115	-	μA	V_R=5V.Ee=5mW/cm^2
Reverse Dark Current	I_D	-	-	30	nA	V_R=30V.Ee=0
Reverse Break down Voltage	$V_{(BR)}$	30	-	-	V	I_R=100μA
Forward Voltage	V_F	-	-	1.2	V	I_F=1mA
Total Capacitance	C_T	-	25	-	PF	V_R=20V.Ee=0,f=1.0MHZ
Rise Time/ Fall Time	tr/tf	-	50	-	ns	V_R=20V,λ=940nm.RL=50Ω

● Typical Optical-Electrical Characteristic Curves

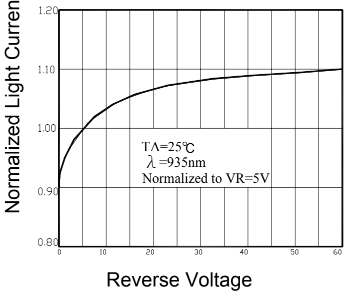
Relative Response vs. Wavelength



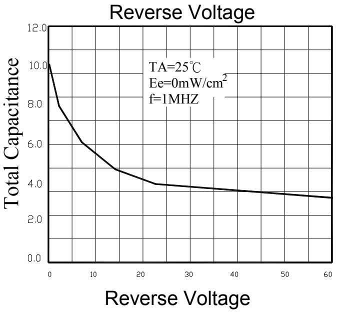
Coupling Characteristics



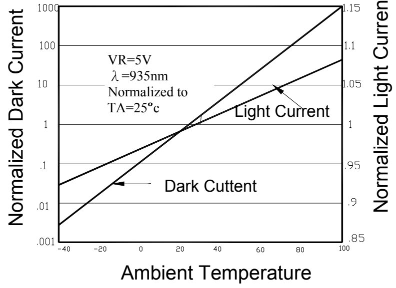
Normalized Light Current vs Reverse Voltage



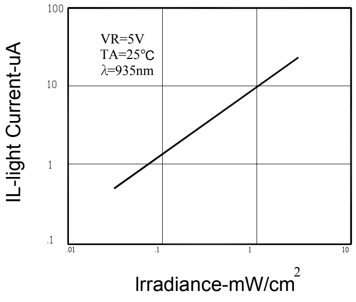
Total Capacitance vs Reverse Voltage



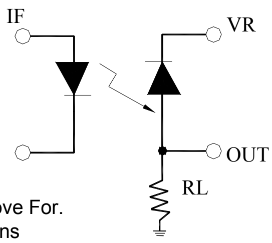
Normalized Light and Dark Current vs Ambient Temperture



Light Current vs. Irradiance



Switching Time Test Circuit



Note:
See Above For.
Conditions

Light Current vs. Angular Displacement